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ELECTRONIC CIRCUIT DEVICE

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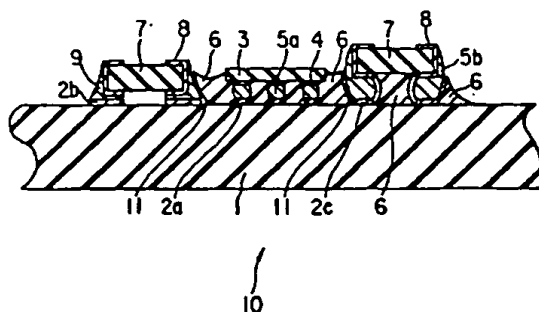
Abstract

Purpose

The present invention offers an electronic circuit device that is able to mount electronic parts such as LSI and passive chip parts on an electronic circuit substrate at high density (parts interval 0.3-5 mm) and with high reliability.

Constitution

This is an electronic circuit device having a wiring substrate, a semiconductor element mounted on this substrate by means of bumps, and passive element parts that are adjacent to this semiconductor element with a parts interval of 5 mm or less and that are mounted on said substrate by means of an electroconductive connecting material, and resin is arranged between said substrate and the semiconductor element and on the periphery of the semiconductor element. It is characterized in that the resin arranged on the periphery of said semiconductor element is arranged separated from the electroconductive connecting material that extends from the surface of the substrate of the resin and that mounts the passive element parts that are contiguous with said semiconductor element on the substrate.



Claim

1. An electronic circuit device having a wiring substrate, a semiconductor element mounted on this substrate by means of bumps, and passive element parts that are adjacent to this semiconductor element with a parts interval of 5 mm or less and that are mounted on said substrate by means of an electroconductive connecting material, and resin is arranged between said substrate and the semiconductor element and on the periphery of the semiconductor element,

characterized in that the resin arranged on the periphery of said semiconductor element is arranged separated from the electroconductive connecting material that extends from the surface of the substrate to the surface of the resin and that mounts the passive element parts that are contiguous with said semiconductor element on the substrate.

2. The electronic circuit device of Claim 1, characterized in that said wiring substrate is made from a resin material.

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